

Tarik Omer Ogurtani

List of Publications by Year in descending order

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18
papers

207
citations

1163117

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996975

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18
all docs

18
docs citations

18
times ranked

77
citing authors

#	ARTICLE	IF	CITATIONS
1	Irreversible thermodynamics of triple junctions during the intergranular void motion under the electromigration forces. <i>International Journal of Solids and Structures</i> , 2005, 42, 3918-3952.	2.7	35
2	Mesoscopic nonequilibrium thermodynamics of solid surfaces and interfaces with triple junction singularities under the capillary and electromigration forces in anisotropic three-dimensional space. <i>Journal of Chemical Physics</i> , 2006, 124, 144706.	3.0	31
3	Computer simulation of void growth dynamics under the action of electromigration and capillary forces in narrow thin interconnects. <i>Journal of Applied Physics</i> , 2001, 90, 1564-1572.	2.5	29
4	Unified theory of linear instability of anisotropic surfaces and interfaces under capillary, electrostatic, and elastostatic forces: The regrowth of epitaxial amorphous silicon. <i>Physical Review B</i> , 2006, 74, .	3.2	22
5	Variational formulation of irreversible thermodynamics of surfaces and interfaces with grain-boundary triple-junction singularities under the capillary and electromigration forces in anisotropic two-dimensional space. <i>Physical Review B</i> , 2006, 73, .	3.2	16
6	Morphological evolution of voids by surface drift diffusion driven by capillary, electromigration, and thermal-stress gradients induced by steady-state heat flow in passivated metallic thin films and flip chip solder joints. I. Theory. <i>Journal of Applied Physics</i> , 2008, 104, 023521.	2.5	14
7	Cathode edge displacement by voiding coupled with grain boundary grooving in bamboo like metallic interconnects by surface drift-diffusion under the capillary and electromigration forces. <i>International Journal of Solids and Structures</i> , 2008, 45, 921-942.	2.7	9
8	Morphological evolution of edge-hillocks on single-crystal films having anisotropic drift-diffusion under the capillary and electromigration forces. <i>Thin Solid Films</i> , 2007, 515, 2974-2983.	1.8	8
9	Morphological evolution in a strained-heteroepitaxial solid droplet on a rigid substrate: Dynamical simulations. <i>Journal of Applied Physics</i> , 2010, 108, .	2.5	8
10	Grain boundary grooving in bi-crystal thin films induced by surface drift-diffusion driven by capillary forces and applied uniaxial tensile stresses. <i>Philosophical Magazine</i> , 2012, 92, 804-829.	1.6	8
11	Thermal grain-boundary grooving in bicrystal thin solid films having strong anisotropic surface Gibbs free energy represented by the modified cycloid-curtate function. <i>Journal of Crystal Growth</i> , 2009, 311, 1584-1593.	1.5	7
12	Generic role of the anisotropic surface free energy on the morphological evolution in a strained-heteroepitaxial solid droplet on a rigid substrate. <i>Journal of Applied Physics</i> , 2010, 108, .	2.5	6
13	Mesoscopic nonequilibrium thermodynamics treatment of the grain boundary thermal grooving induced by the anisotropic surface drift diffusion. <i>Journal of Materials Science</i> , 2011, 46, 6054-6064.	3.7	6
14	Void Intergranular Motion Under the Action of Electromigration Forces in Thin Film Interconnects with Bamboo Structure. <i>Materials Research Society Symposia Proceedings</i> , 2001, 695, 1.	0.1	4
15	Mesoscopic irreversible thermodynamics of morphological evolution kinetics of helical conformation in bioproteins "DNA"™ under the isothermal isobaric conditions. , 2020, 4, 009-019.		2
16	Computer Simulations on the Grain Boundary Grooving and Cathode Edge Displacement in Bamboo-like Metallic Interconnects. <i>Materials Research Society Symposia Proceedings</i> , 2006, 914, 1.	0.1	1
17	Effects of anisotropic surface drift diffusion on the strained heteroepitaxial nanoislands subjected to electromigration stressing. <i>Journal of Applied Physics</i> , 2022, 131, 075301.	2.5	1
18	The Effect of Initial Void Configuration on the Morphological Evolution Under the Action of Normalized Electron Wind Forces. <i>Materials Research Society Symposia Proceedings</i> , 2001, 714, 921.	0.1	0